ABSTRACT OF THE INVENTION

An improved heat sink structure, having a heat dissipating member and a board member on which the heat dissipating member is mounted. The board member has an upper board and a lower board. A plurality of recessed connecting structures is formed on the top surface of the upper board. The heat dissipating member has a plurality of fins and air circulating channels between the fins. A plurality of protruding embedding structures is formed on the bottom of the fins, such that the heat dissipating member can be secured to the top surface by the connecting parts and the inserting parts. Thereby, the heat dissipating member can be secured to the board member as an integral unit. The structure strength, attachment and conducting performance can thus be enhanced.